FUĴĨTSU

PRIMERGY RX300 S8

System configurator and order-information guide

September 2015

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Change report



PRIMERGY Server

Instructions

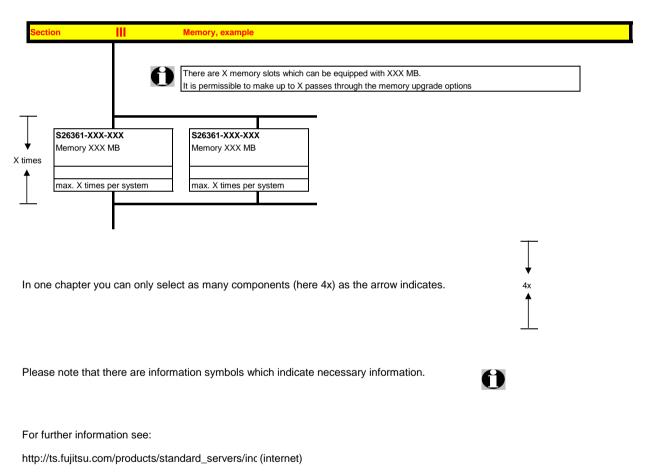
This document contains basic product and configuration information that will enable you to configure your system via PC-/System-Architect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.

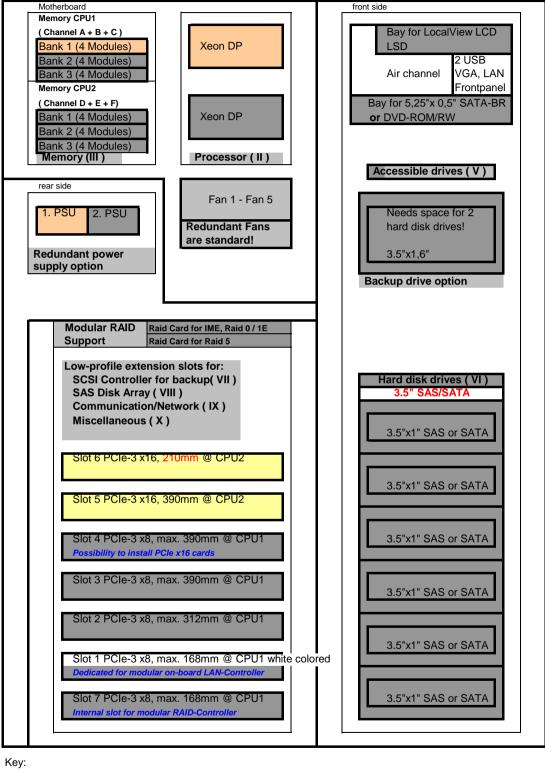


https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/current/Pages/default.aspx (extranet)

Configuration diagram PRIMERGY RX300 S8

System unit (I)

with up to 6x 3.5" Hard disk drives



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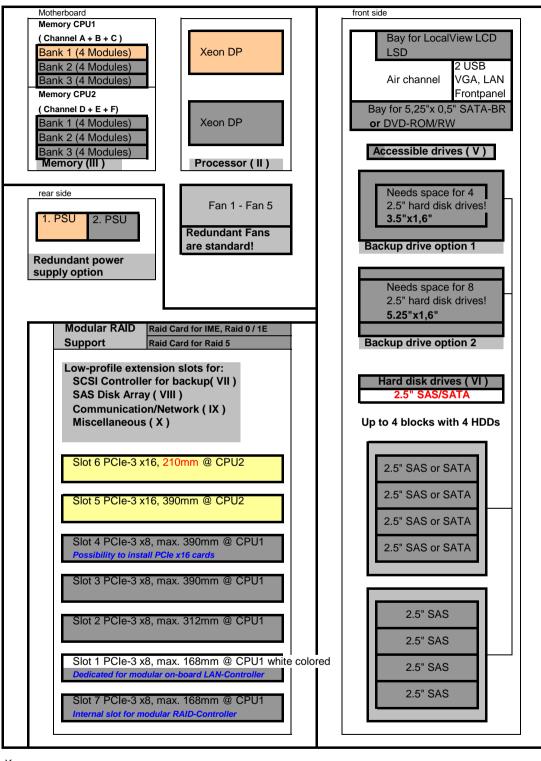
Included in basic unit

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Option

Configuration diagram PRIMERGY RX300 S8

System unit (I)



with up to 4, 8, 12 or 16x 2.5" Hard disk drives or up to 4 or 8 PCIe SSDs 2.5"

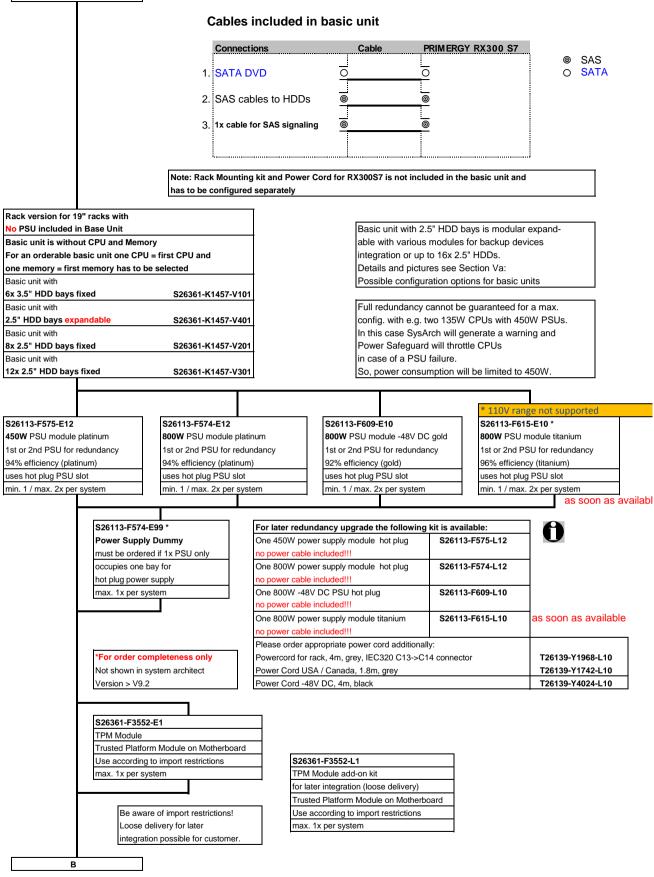
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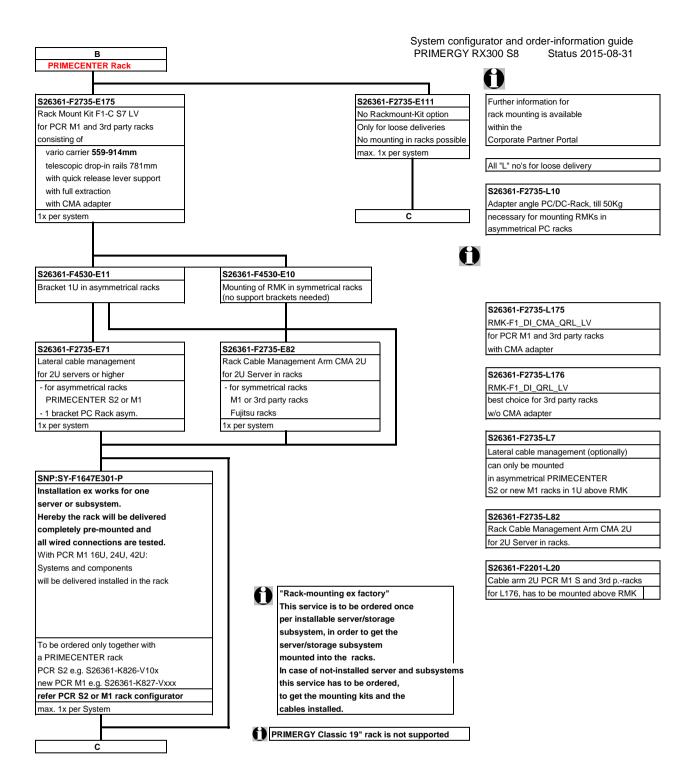
Included in basic unit

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Option

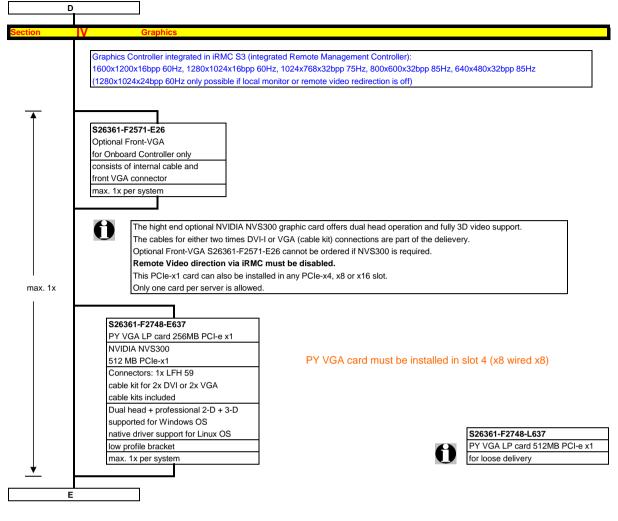
Start PRIMERGY RX300	S8	PRIMERGY RX300 S8	Status 2015-08-31
Section		Basic unit	
	Cur.	tem unit consisting of:	
		I Housing without power supply modules	
		isic units with:	
	- 2	2 Hot-Plug Power Supply Bays	
	- 5	5 Fans (full redundancy)	
		2 memory DIMMs per CPU (max 768GB) => Total 24 DIMMs (max 1536GB) for two CPU's	
		AS Backplane for 6x 3.5" HD, SAS Backplanes for 4, 8, 12 or 16x 2.5" HD or PCIe Backplanes for	
	4	or 8 PCIe SSD with cable connection to on-board, modular RAID Controller	
	* Dr	ives/Bays	
		- 6 bays 1" for hot plug 3.5" HD (1" high) or 4, 8, 12 or 16 bays for hot plug 2.5" HD	
		- 1 bay for 3.5" and 1.6" high Backup device, consumes 2 bays for 3.5" HD for basic unit 6x 3.5" HD	
		not possible for basic unit with 12 or 16 x 2,5" HD	
		 1 bay for 5.25" and 1.6" high Backup device, not possible for basic unit 6x 3.5" HD for basic unit with 12 or 16 x 2,5" HD 	
		- 1 bay SATA-CD- or DVD-ROM 0,5" height (option)	
		- 1 bay for opt. LocalView LC-Display	
		egrated ServerView Diagnostics Technology (Diagnosis LED's) for indication of internal	
	fai	led components	
	Sve	temboard D2939-B with:	———————————————————————————————————————
	-	o to two Xeon DP CPU`s (Socket-R)	
	-	th 2 serial QPI links (Quick Path Interconnect) and four memory channels per CPU	
		rst CPU has to be selected for an orderable basic unit,	
	* Cł	nipset Intel® C600 Series (codenamed Patsburg)	
	* 7	PCI slots: - 2x PCIe-3 x16 (both slots are connected to CPU 2 and are useable with configure	d 2nd CPU only!)
		 - 4x PCIe-3 x8 (one notched to install x16 cards) - 1x PCIe-3 x8 (for internal modular RAID controller only) 	
	* 24	memory slots for max. 1536GB RAM DDR3 available	
	- 1	Memory is divided into 12 DIMMs per CPU (4 channels with 3 slots per channel)	
		Possible max. configurations are:	
		16x 8GB UDIMM (dual rank modules) = 128GB	
		24x 16GB RDIMM (dual rank modules) = 384GB	
		24x 32GB LRDIMM (quad rank modules) = 768GB 24x 64GB LRDIMM (eight rank modules) = 1536GB	
		First Memory (one module) has to be selected for an orderable basic unit per CPU	
		Memory upgrade is possible module wise	
	- 1	Memory mirrroring is supported with 2 identical modules in channel A+B CPU 1 or D+E CPU 2	
		Hot Spare Memory is supported with 3 identical modules in channel A+B+C CPU 1 or D+E+F CPU	2
	- 9	SDDC (Chipkill) is supported for memory modules,	
	* D.	us Dest 10/100/1000 v1 DCI Everaget Circhit Ethernet Intel I AN centralier Dewarville on beard	
		I Port 10/100/1000 x4 PCI Express* Gigabit Ethernet Intel LAN controller Powerville on-board MC S4 (integrated Remote Management Controller) on-board server management controller with	
		dicated 10/100/1000 Service LAN-port and integrated graphics controller.	
		e Service LAN-port can be switched alternatively on standard Gbit LAN port 1	
		aphics Controller integrated in iRMC S4 (integrated Remote Management Controller):	
		00x1200x16bpp 60Hz, 1280x1024x16bpp 60Hz, 1024x768x32bpp 75Hz, 800x600x32bpp 85Hz,	
		0x480x32bpp 85Hz 280x1024x24bpp 60Hz only possible if local monitor or remote video redirection is off)	
		warrazaapp winz only possible in local monitor of remote video reunection is OII)	
	Inte	rfaces at the rear:	
	* 1x	RS-232-C (serial, 9 pins) (usable for BMC or OS or shared)	
		VGA (15 pins)	
		USB 2.0 (UHCI) with 480MBit/s, no USB wakeup	
	* 2x	LAN RJ45, 1x Service-LAN RJ45	
	Inte	rfaces on the front:	
		USB 2.0 (UHCI) with 480MBit/s, no USB wakeup	
		VGA (15 pins) as an option	
		Service-LAN RJ45 as an option	
		<u>.</u>	
		rfaces internal:	
		released internal USB Interfaces for backup devices, USB 2.0 (UHCI) with 480MBit/s for dongle funcionality (uSSD memory), no USB wakeup	
		SATA interface for DVD (only usable with 4x 2.5" HDD + DVD Option)	
		SATA/SAS interface for 4 SATA/SAS HD's or SAS Backup device	
		USB 2.0 ports for internal USB redirection connected to BMC	
		tware:	
		erverView Suite Software package incl. ServerStart, ServerBooks, Management Software and Upd	ates
	* Do	ocumentation engl. (multilingual on CD)	
A			



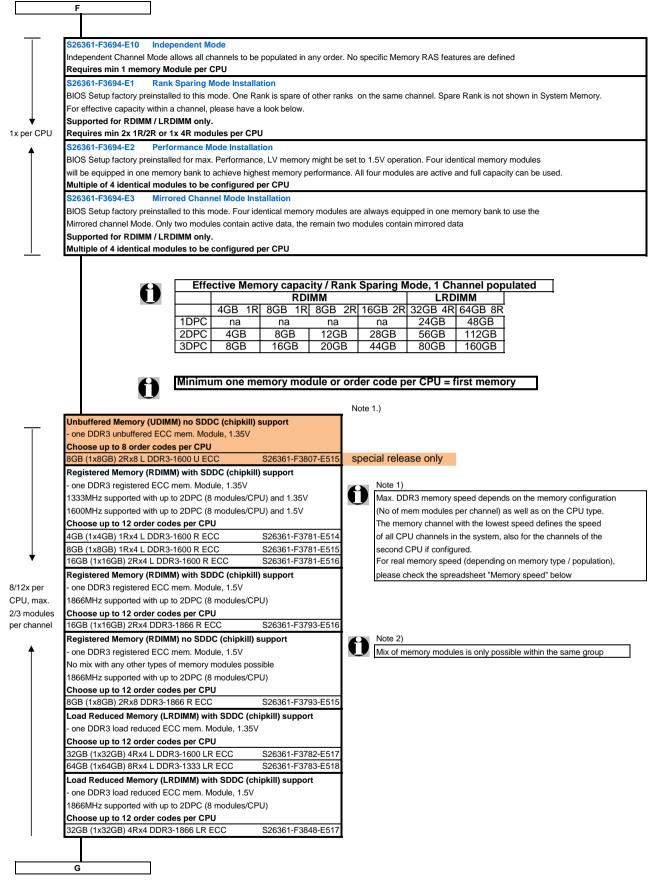


Section Processor		
There are 2 processor sockets available.		1
The first socket must always be equipped with	the first CPU which can be	selected via configurator
It is also possible to upgrade a dual-processo		•
Both PCIe-3 x16 slots are connected to CF	•	
Two processors with different clock frequ		sonngureu zhu CFO onny:
A multi-processor operating system is require	•	m
A multi-processor operating system is require		11.
		1
Max. two CPU's can be selected per basic unit		
One of following CPU's has to be selected as first CPU		
for an orderable basic unit Optional second CPU has to be the same type like the first CPU		
Basic 4C CPU's		Max. DDR3 Bus Speed depends on:
- 1x 64-bit Intel Xeon (10MB Smart Cache)		Max. DDR3 Bus Speed depends on: - max. DDR3 Bus Speed from the CPU and
1333 MHz DDR3 Bus; 6,40 GT/s QPI Bus and passive heat sink		- max. DDR3 Bus Speed from the CPO and - max. DDR3 Memory Speed and
occupies socket for one CPU		- max. memory modules on one memory channel
Xeon E5-2603v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E180	For CPUs which do not offer 1866 MHz support,
Xeon E5-2609v2 4C/4T 2.50GHz 10MB 6.40GT/s 1333MHz 80W	S26361-F3788-E250	(Basic, Standard & Low Power class),
Standard Turbo 6C/8C CPU's		System Architect will not offer memory modules
- 1x 64-bit Intel Xeon (15/20MB Smart Cache); Hyper-Threading (HT);		supporting this frequency.
1600 MHz DDR3 Bus; 7,20 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2620v2 6C/12T 2.10GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E210	
Xeon E5-2630v2 6C/12T 2.60GHz 15MB 7.20GT/s 1600MHz 80W	S26361-F3789-E260	
Xeon E5-2640v2 8C/16T 2.00GHz 20MB 7.20GT/s 1600MHz 95W	S26361-F3789-E200	
Advanced Turbo+ 8C/10C CPU`s		
- 1x 64-bit Intel Xeon (20/25MB Smart Cache); Hyper-Threading (HT);		
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2650v2 8C/16T 2.60GHz 20MB 8.00GT/s 1866MHz 95W	S26361-F3790-E260	
Xeon E5-2660v2 10C/20T 2.20GHz 25MB 8.00GT/s 1866MHz 95W	S26361-F3790-E220	
Xeon E5-2670v2 10C/20T 2.50GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E250	
Xeon E5-2680v2 10C/20T 2.80GHz 25MB 8.00GT/s 1866MHz 115W	S26361-F3790-E280	
Xeon E5-2690v2 10C/20T 3.00GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3790-E300	
Segment Optimized CPU's		
- 1x 64-bit Intel Xeon (15/25/30MB Smart Cache); Hyper-Threading (HT);		
1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2637v2 4C/8T 3.50GHz 15MB 8.00GT/s 1866MHz 130W	S26361-F3791-E350	
Xeon E5-2643v2 6C/12T 3.50GHz 25MB 8.00GT/s 1866MHz 130W Xeon E5-2667v2 8C/16T 3.30GHz 25MB 8.00GT/s 1866MHz 130W	S26361-F3791-E330 S26361-F3791-E300	
Xeon E5-266/V2 8C/161 3.30GHZ 25MB 8.00G1/s 1866MHZ 130W Xeon E5-2695v2 12C/24T 2.40GHz 30MB 8.00GT/s 1866MHz 115W	S26361-F3791-E300 S26361-F3791-E240	
Xeon E5-2695V2 12C/241 2.40GHz 30MB 8.00GT/s 1866MHz 115W Xeon E5-2697v2 12C/24T 2.70GHz 30MB 8.00GT/s 1866MHz 130W	S26361-F3791-E240 S26361-F3791-E270	
Low Power 6C/10C CPU's	C_000. 10101 L210	
- 1x 64-bit Intel Xeon (15/25MB Smart Cache); Hyper-Threading (HT);		
1600 MHz DDR3 Bus; 7,20/8,00 GT/s QPI Bus and passive heat sink		
occupies socket for one CPU		
Xeon E5-2630Lv2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W	S26361-F3792-E240	
Xeon E5-2650Lv2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 70W	S26361-F3792-E170	
		1
D		

С



ter Memory area in a final memory slots per CPU for max. Tradea LUNN (122 4/08 8/1) USGR RUMM	_		PRIMERGY RX300 S8	Status 2015-08-
• There are 12 memory slots per CPU for max. 760GB LADIMM (12x 16GB 2R) 192GB ROIMM (12x 16GB 2R) 193GB LOIMM (12x 16GB 2R) 193GB LOI	E			
 786GL LEDIMM (12: K 4GB R); 19205 RDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); The memory area is divided into 4 channels per CPU win 3 slots per channel Six 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3. Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, I cad reduced and unbuffered modules allowed. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory operating voltage can be set within BIOS (1,5% is default sating for max. speed). In 35% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) 1.33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 3 30 DIMMs per channel configuration, memory will operate at 1.35% or 15% (no UDIMM allowed). SDD (Channels can be populated in any order in Independent Channel Mode. All four channels must that the same interface frequency but individual channels may run at different DIMM timinge (RAS I stancy, CAS I stancy, and as of onth) No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration possible Oblis set to the rank sparing setting. Minimum configuration is: X 4 that RAS D	ection	M	emory	
 786GL LEDIMM (12: K 4GB R); 19205 RDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); The memory area is divided into 4 channels per CPU win 3 slots per channel Six 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3. Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, I cad reduced and unbuffered modules allowed. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory operating voltage can be set within BIOS (1,5% is default sating for max. speed). In 35% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) 1.33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 3 30 DIMMs per channel configuration, memory will operate at 1.35% or 15% (no UDIMM allowed). SDD (Channels can be populated in any order in Independent Channel Mode. All four channels must that the same interface frequency but individual channels may run at different DIMM timinge (RAS I stancy, CAS I stancy, and as of onth) No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration possible Oblis set to the rank sparing setting. Minimum configuration is: X 4 that RAS D				
 786GL LEDIMM (12: K 4GB R); 19205 RDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); Sedge UDMM (12: K 4GB R); The memory area is divided into 4 channels per CPU win 3 slots per channel Six 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3. Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, I cad reduced and unbuffered modules allowed. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory can be operated at 15% or 135% (veri) if the modules are of low voltage type. Memory operating voltage can be set within BIOS (1,5% is default sating for max. speed). In 35% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) 1.33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 33% -1330MH zmax (depending on CPU, up to two LRDIMM per channel) In 3 30 DIMMs per channel configuration, memory will operate at 1.35% or 15% (no UDIMM allowed). SDD (Channels can be populated in any order in Independent Channel Mode. All four channels must that the same interface frequency but individual channels may run at different DIMM timinge (RAS I stancy, CAS I stancy, and as of onth) No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration No mix of registered, foad reduced and unbuffered modules allowed. 21 "Rank Sparing Mode" configuration possible Oblis set to the rank sparing setting. Minimum configuration is: X 4 that RAS D		- There	a are 12 memory slots per CPII for may	
1920B RDMM (12x 190B as pseudo Relesse only ⇒ max. 1.5380B for two CPU's (7680B per CPU), using LRDIMM - The memory area is divided into 4 channels per CPU with 3 slots per channel - Sito 1 of each channel bloogs to memory bank 1, the slot 2 belongs to memory bank 2, stol 3 belongs to memory bank 3 Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, IG and reduced and unbuffered medules allowed. Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type. Memory operating voltage can be set within BIOS (1.5V is default setting for max, seped). In a single DIMM per channel configuration, following frequencies are supported: -1.5V - 1806MHz max (depending on CPU) -1.3V - 1803MHz max (up to two UDIMM or RDIMM per channel) -1.3V - 1803MHz max (up to two UDIMM or RDIMM per channel) -1.3V - 1803MHz max (up to two UDIMM or RDIMM per channel) SSD (Chipkill) is supported for registered / load reduced x4 organized memory modules only. SSD (Chipkill) RES lateop, CAS Stateop, CAS Stateop, And				
Bit State State				
 > max. 1.5366 for two CPU 3 (F868 per CPU) using LRDIMM The memory area is divided into 4 channels per CPU with 3 solts per channel. Ski 1 of each channel belongs to memory bank 1, the skin 2 belongs to memory bank 2, skin 3 belongs to memory bank 3 Registered, LR DIMMs and unbuffered memory modules allowed. Memory can be operated at 1.50 vr 1.50°, even if the modules allowed. Memory can be operated at 1.50 vr 1.50°, even if the modules are of low voltage type. Memory operating voltage can be set within IDO (1.50° at defutul setting for max. speed). In a single DIMM per channel configuration, following frequencies are supported: 1.50° - 1866MHz max (depending on CPU) 1.33° vi 1000MHz max (depending on CPU) 1.33° vi 1000MHz max (depending on CPU) 1.33° vi 1000MHz max (depending on CPU) 1.35° vi 1.350 MHz per channel configuration, memory will operate at 1.35° vi 1.5° (no UDIMM allowed). SSD (Chipkill) is supported for registered / load reduced x4 organized memory modules only. 1. In the "Independent Channel Mode" is following configuration possible Channels may be populated in any order in dhapen der Channel Mode. All four channels may turn at the same interface frequency but individual channels may turn at different DIMM timing (RAS latency, and so tom!) No mix of registered, load reduced and unbuffered modules allowed. 2) "Rank Sparing Mode" configuration Within a memory channel, please refer to the spreadshee below. The BIOS is set to the max, sperofmance to memory modules of mininym configuration is: 4 x 18,				
- The memory area is divided into 4 channels per CPU with 3 stots per channel - Stot 1 of each channel belongs to memory bank 1, the stot 2 belongs to memory bank 2, stot 3 belongs to memory bank 3 Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, load reduced and unbuffered medules allowed. Memory operating voltage can be set within BIOS (1.5V is default setting for max speed). In a single DIMM per channel configuration, following frequencies are supported: -1.5V - 1866Mir/x max (depending on CPU) -1.3SV -11600Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -11600Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.3SV -1133Mir/x max (depending on CPU, pto two LRDIMM per channel) -1.9 Intermined populated in any order in Independent Channel Mode. All our channels must performance frequence ybuit individual channels may r				
 Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3 Registered, LR DIMMs and unbuffered memory modules can be selected No mix of registered, load reduced and unbuffered modules allowed. Memory can be operated at 1.5V or 1.3V, even if the modules are of low voltage type. Memory can be operated at 1.5V or 1.3V, even if the modules are of low voltage type. Memory can be operated at 1.5V or 1.3V, even if the modules are of low voltage type. Memory can be operated at 1.5V or 1.0V to LRDIMM per channel) 1.3SV 1303MHz max (dpending on CPU, up to to LRDIMM per channel) 1.3SV 1303MHz max (up to two UDMM or RDUMM per channel) 1.3SV 1333MHz max (up to two UDMM or RDUMM per channel) 1.3 bilMs per channel configuration, memory will operate at 1.3SV or 1.5V (no UDIMM allowed). SSD (Chipkill) is supported for registered / load reduced x4 organized memory modules only. 1.1 In the "independent Channel Mode" is following configuration possible Channels can be populated in any order in Independent Channel Mode. All four channels may true at different DIMM timings (RAS latency, CAS latency, and so forth) No mix of registered, load reduced and unbuffered modules allowed. 2.) "Rank Sparing Mode" configuration Within a memory channel, one rank is a spare of the other ranks. The Spare Rank is held in reserve and is not available as system memory For the effective memory capacity, please refer to the spreadsheet below. The BIOS is set to the rank sparing setting. Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel This mode is not supported by unbuffered memory modules 3.) "Performance Mode" configuration In this configuration, is: 2x 1R, 2x 2R o				
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This mode is not supported by unbuffered memory modules				
		Minin	num configuration is: 4x identical modules	
F		This	mode is not supported by unbuffered memory modules	
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r				
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Memory Configuration PRIMERGY RX300 S8

Each CPU offers 12 Slots for DDR3 Memory Modules organised in 3 Banks and 4 Channels. If you need more than 12 Slots you have to configure the 2nd CPU. Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application
		ODIMIN	RUIWIW	LRDIMM	
		x8	x8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

*) For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x4GB	1x4GB	1x32GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x64GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	1536GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus s					speed depending on CPU type, memory configuration (I and voltage setting (BIOS)							OPC)					
	UDIMM 1866MHz			RDIMM 1866MHz				LRDIMM 4R 1866MHz										
Voltage setting (BIOS)	1.5\	/ [defa	ault]	1.35V		1.5\	1.5V [default] 1.35V		/	1.5V [default]		ault]	1.35V					
	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1866MHz DDR3 Bus	1866	1600	-	1333	1333	-	1866	1866	1066	1333	1333	800	1866	1866	1066	1600	1600	1066
CPU with 1600MHz DDR3 Bus	1600	1600	-	1333	1333	-	1600	1600	1066	1333	1333	800	1600	1600	1066	1600	1600	1066
CPU with 1333MHz DDR3 Bus	1333	1333	-	1333	1333	-	1333	1333	1066	1333	1333	800	1333	1333	1066	1333	1333	1066

1R - Single Rank 4R - Quad Rank 2R - Dual Rank 8R - Eight Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel 3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

Bank I black sockets

Bank II blue sockets Bank III

green sockets

Bank I on CPU 1/2 Bank II on CPU 1/2 Bank III on CPU 1/2

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below) up to 4 memory modules connected to Channel A - H on the 1st/2nd CPU

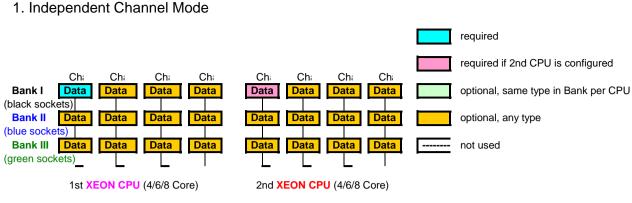
up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU

up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU

(can not be populated by UDIMM or 4R RDIMM memory modules)

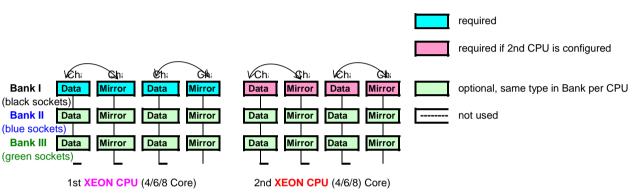
- See below and next page for a detailed descriptions of the memory configuration supported.

System configurator and order-information guide PRIMERGY RX300 S8 Status 2015-08-31



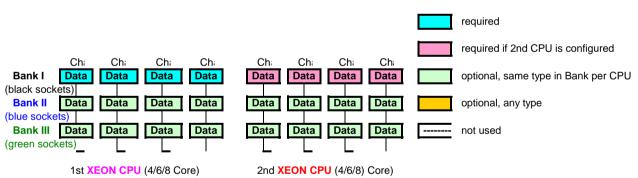
Independent Channel Mode allows all channels to be populated in any order Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



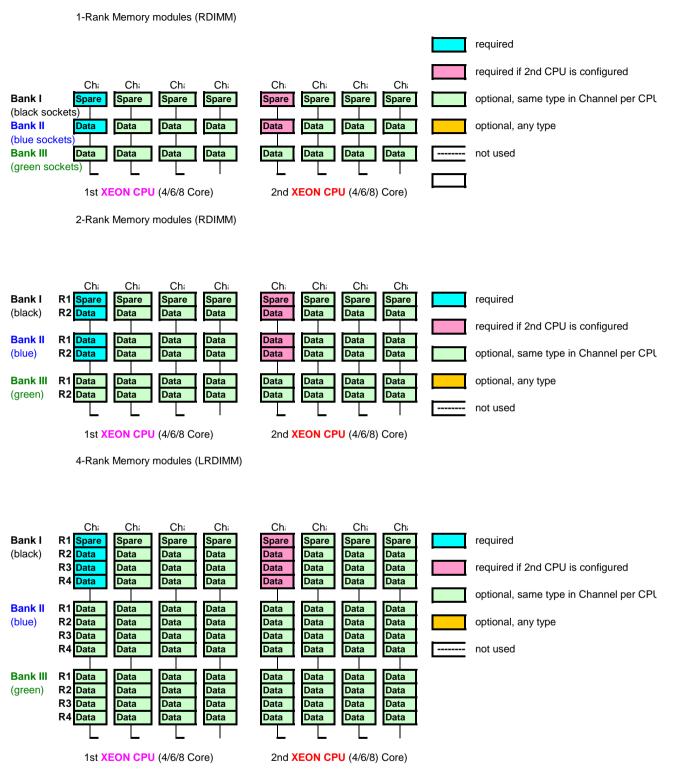
Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 4 identical modules has to be ordered.

3. Performance Channel Mode



Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 4 identical modules has to be ordered.

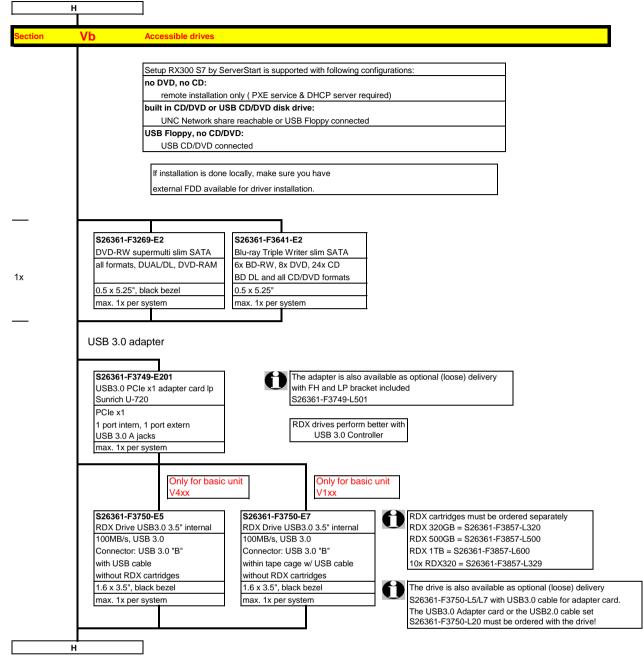
4. Rank Sparing Mode



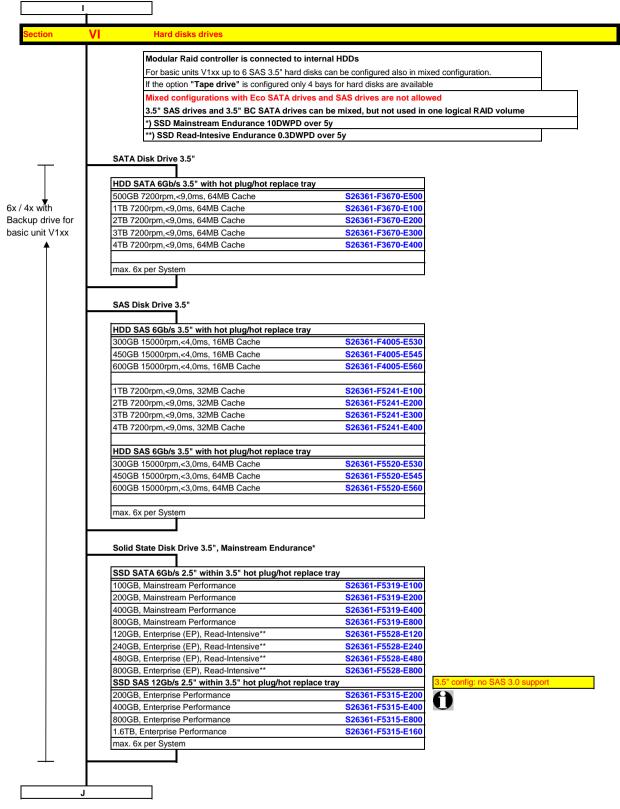
Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

The second se	Config 1: 6x or 4x 3.5" HDD + 3.5" DD	S/RDX drive
	Is fixed due to selection of basic unit with 6x 3,5" HDD bays fixed	S26361-K1457-V10
	SAS3.0 available since Q2/2014	no PCIe SSD SF
-		
	Basic unit S26361-K1457-V401 with Config 2: 4x 2.5" HDD	expandab S26361-F1373-E42
DEPENDENT DEPENDENT DEPENDENT DEPENDENT DE		
	Available Upgrade kits for this configurat Upgrade kit to 8x 2.5" HDD	ion option: S26361-F1373-L42
	Upgrade kit to 12x 2.5" HDD	S26361-F1373-L42
	Upgrade kit to 4x 2.5" HDD + LTO	S26361-F1373-L4
	Upgrade kit to 4x + 8x 2.5" SAS3.0	S26361-F1373-L5
	Basic unit S26361-K1457-V401 with	expandab
	Config 3: 4x 2.5" HDD + LTO	S26361-F1373-E43
	Basic unit S26361-K1457-V401 with	expandat
	Available Upgrade kits for this configurat	ion option:
	Upgrade kit to 8x 2.5" HDD	S26361-F1373-L4
	Basic unit S26361-K1457-V201 with	
	Config. 4: 8x 2,5" HDD bays fixed	S26361-K1457-V2
	Available Upgrade kits for this fixed confi	-
	Upgrade kit to 12x 2.5" HDD	S26361-F1373-L24 S26361-F1373-L24
	Upgrade kit to 16x 2.5" HDD	320301-F13/3-L24
	Basic unit S26361-K1457-V401 with	expandab
	Config 5: 8x 2.5" HDD + 3.5" drive	S26361-F1373-E45
	Config 12: 3.5" drive + 8x SAS3.0	S26361-F1373-E55
	No Upgrade kit available!	
	Basic unit S26361-K1457-V401 with	expandab
	Config 6: 8x 2.5" HDD + LTO	S26361-F1373-E4
A CONTRACT OF A	Config 15: LTO + 8x SAS3.0	S26361-F1373-E5
	no ODD and LSD bay available!	
	No Upgrade kit available!	
	Basic unit S26361-K1457-V301 with	
	Config 7: 12x 2,5" HDD bays fixed	S26361-K1457-V3
These sectors with the sector sector	Basic unit S26361-K1457-V401 with Config 10: 4x SAS2.0 + 8x SAS3.0	expandab S26361-F1373-E5
	Note: 4x SAS2.0 + 8x SAS3.0 Note: 4x SAS2.0 connected to on-boa	
	Available Upgrade kits for this configurat	
	Upgrade kit to 16x 2.5" HDD	S26361-F1373-L37
A		
	Basic unit S26361-K1457-V401 with	expandab
	Config 8: 16x 2.5" HDD	S26361-F1373-E48
	no ODD and LSD bay available! No Upgrade kit available!	
		cknlanes and cobles
	Includes all necessary bezels, cages, ba	cryialies and cables

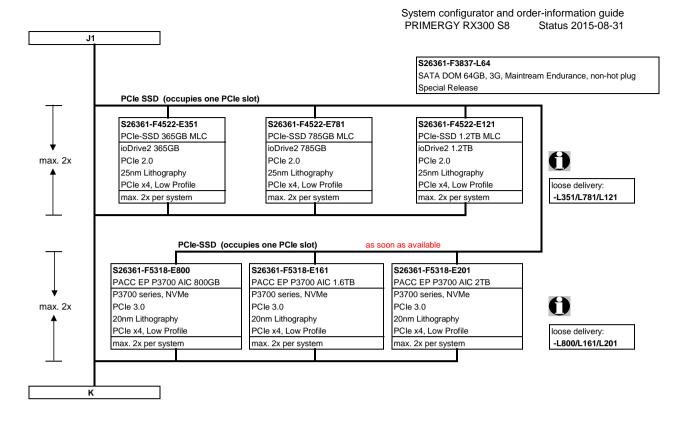
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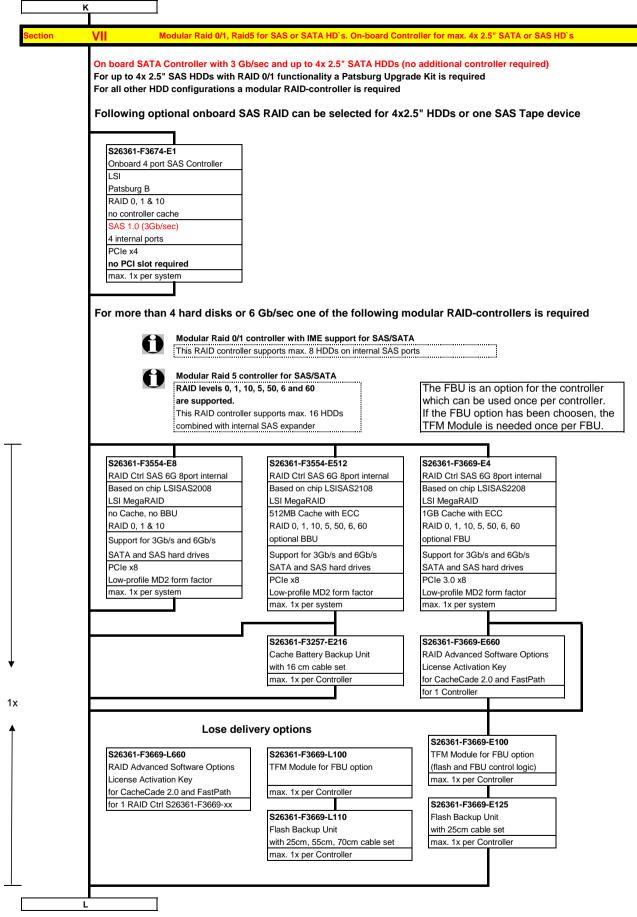


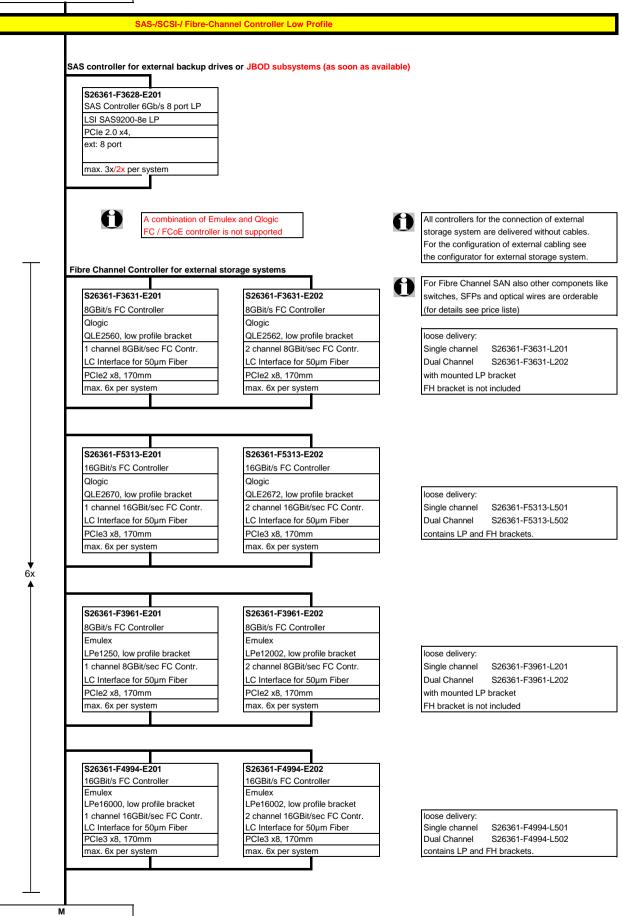
	S26361-F3674-E1	For external SAS Back	un drives
	Onboard 4 port SAS Controller		troller has to be configured
	LSI		
	Patsburg B	Only for basic unit	
	RAID 0, 1 & 10	V4xx	
	no controller cache		
	SAS 1.0 (3Gb/sec)		
	4 internal ports		
	PCle x4		
	no PCI slot required		
	max. 1x per system		
			as soon a
	S26361-F3626-E2	S26361-F3627-E1	S26361-F3787-E1
	Tape drive LTO4 HH SAS IBM V2	Tape drive LTO5HH Ultrium SAS	Tape drive LTO6HH Ultrium SA
	800GB, 120MB/s, SAS 6Gb	1500GB, 140MB/s, SAS 6Gb	2500GB, 160MB/s, SAS 6Gb
	Connector: mini-SAS	Connector: mini-SAS	Connector: mini-SAS
		incl. SAS cable	incl. SAS cable
1x	incl. SAS cable		incl. cleaning cartridge
1x	incl. SAS cable incl. cleaning cartridge	incl. cleaning cartridge	nion. olounning our mugo
1x		incl. cleaning cartridge without data cartridge	without data cartridge
1x	incl. cleaning cartridge		• •



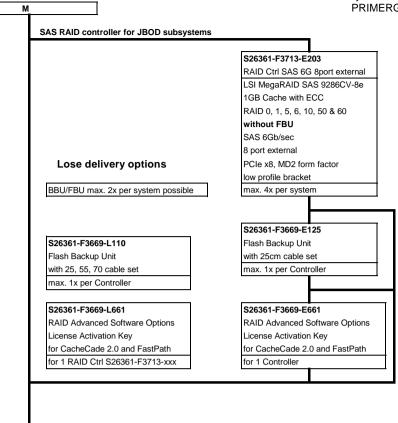
J			
	Solid State Disk 2.5", Mainstream Endurance*		
—	SSD SATA 6Gb/s 2.5" with hot plug/hot replace tray		
	100GB MLC, Mainstream Performance	S26361-F5225-E100	as long as stock
	200GB MLC, Mainstream Performance	S26361-F5225-E200	as long as stock
	400GB MLC, Mainstream Performance	S26361-F5225-E400	as long as stock
	100GB, Mainstream Performance	S26361-F5303-E100	
	200GB, Mainstream Performance 400GB, Mainstream Performance	S26361-F5303-E200 S26361-F5303-E400	
	800GB, Mainstream Performance	S26361-F5303-E800	
	120GB, Enterprise (EP), Read-Intensive**	S26361-F5524-E120	as soon as available
	240GB, Enterprise (EP), Read-Intensive**	S26361-F5524-E240	as soon as available
	480GB, Enterprise (EP), Read-Intensive**	S26361-F5524-E480	as soon as available
	800GB, Enterprise (EP), Read-Intensive**	S26361-F5524-E800	as soon as available
	SSD SAS 6Gb/s 2.5" with hot plug/hot replace tray		
	100GB MLC, Enterprise Performance	S26361-F4581-E100	as long as stock
	200GB MLC, Enterprise Performance	S26361-F4581-E200	as long as stock
	max. 8/12/16x per system		
-			
	Solid State Disk Drive, Mainstream Endurance*		
	SSD SAS 12Gb/s 2.5" with hot plug/hot replace tray		
	200GB, Enterprise Performance	S26361-F5297-E200	Interface SAS12Gb/s and SAS 6Gb/s.
	400GB, Enterprise Performance	S26361-F5297-E400	SAS 12Gb/s support only with PRAID
	800GB, Enterprise Performance	S26361-F5297-E800	EP400i (Cougar4), *F5243-E1
	1.6TB, Enterprise Performance	S26361-F5297-E160	and max. 8x per System
	max. 8/12/16x per system, max. 8x 12Gb/s support		
_			
	SAS Disk Drive 2.5"		
+	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray		
tor V2xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E130	
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache 450GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145	
	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160	
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190	
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160	
V3xx,	HDD SAS 66b/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112	
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514	A
V3xx,	HDD SAS 66b/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112	ð
V3xx,	HDD SAS 66b/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514	HDD 512e
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530	HDD 512e 512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500	
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5521-E130	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E160	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E190	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E160	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E140 S26361-F5551-E112	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E160 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E190	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E140 S26361-F5551-E112	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E140 S26361-F5551-E112	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E140 S26361-F5551-E112	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5228-E100 S26361-F5551-E130 S26361-F5551-E140 S26361-F5551-E112	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E112 S26361-F5554-E118	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E112 S26361-F5551-E112 S26361-F5554-E118 S26361-F5544-E118 S26361-F5544-E118	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E112 S26361-F5551-E112 S26361-F55544-E118 S26361-F5544-E118 S26361-F5544-E118	512e drives are not supported with
V3xx,	HDD SAS 6Gb/s 2.5" with hot plug/hot replace tray 300GB 10000rpm,<4,5ms, 32MB Cache	S26361-F5247-E145 S26361-F5247-E145 S26361-F5247-E190 S26361-F5247-E112 S26361-F4482-E514 S26361-F4482-E530 S26361-F5228-E500 S26361-F5528-E100 S26361-F5551-E130 S26361-F5551-E130 S26361-F5551-E112 S26361-F5551-E112 S26361-F55544-E118 S26361-F5544-E118 S26361-F5544-E118	512e drives are not supported with



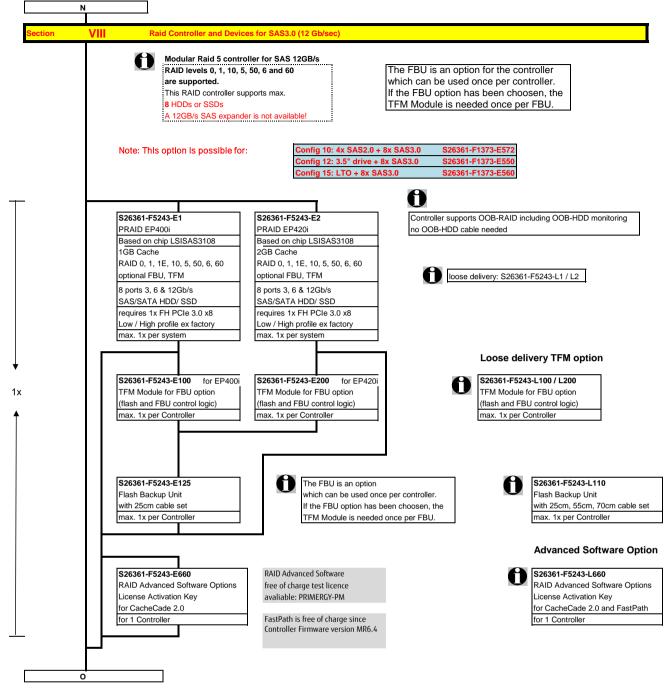


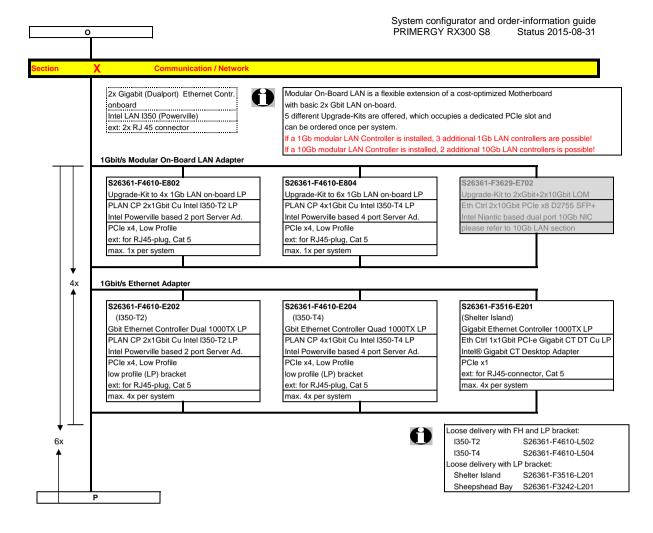


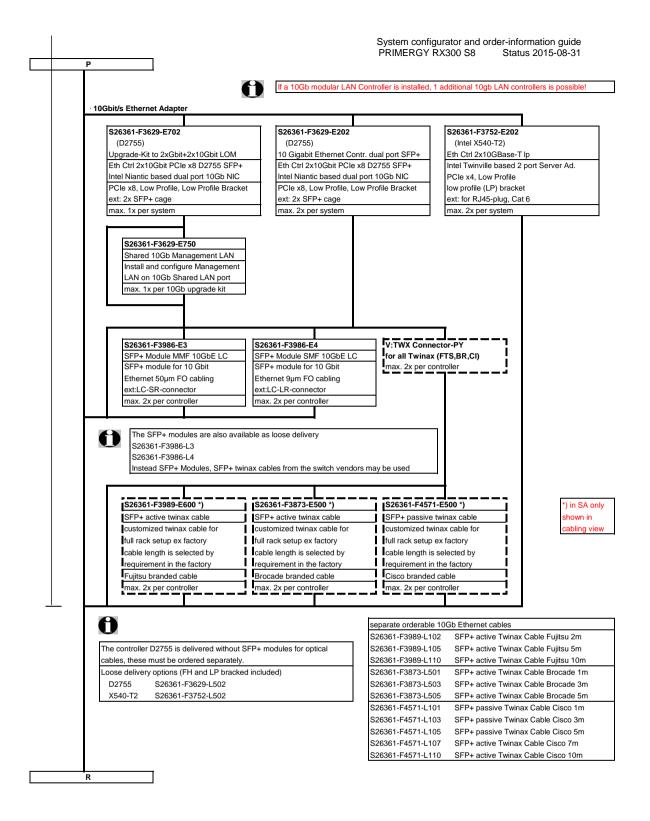
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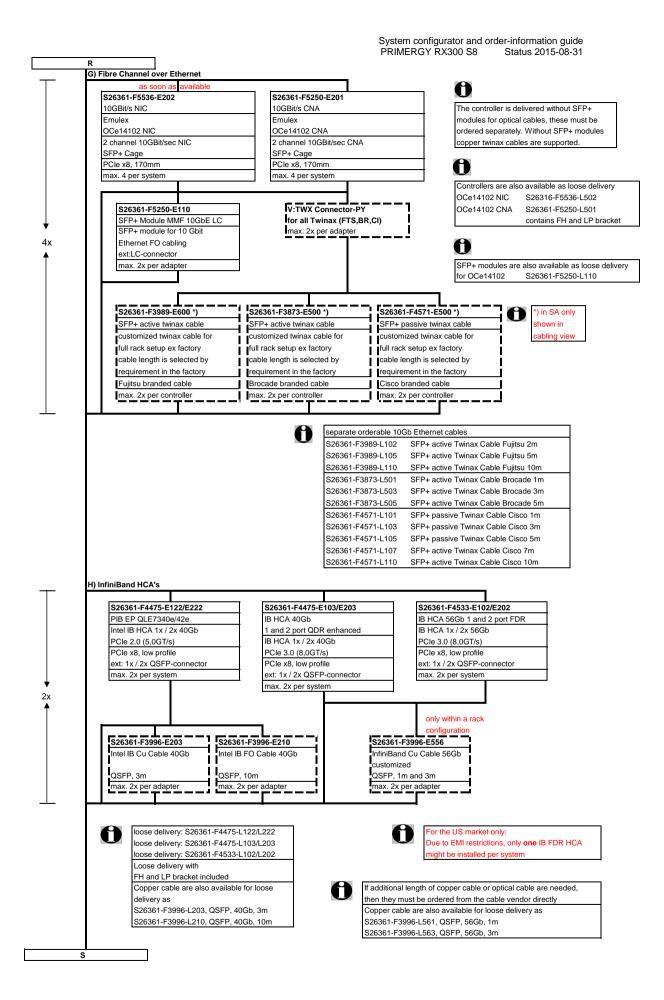


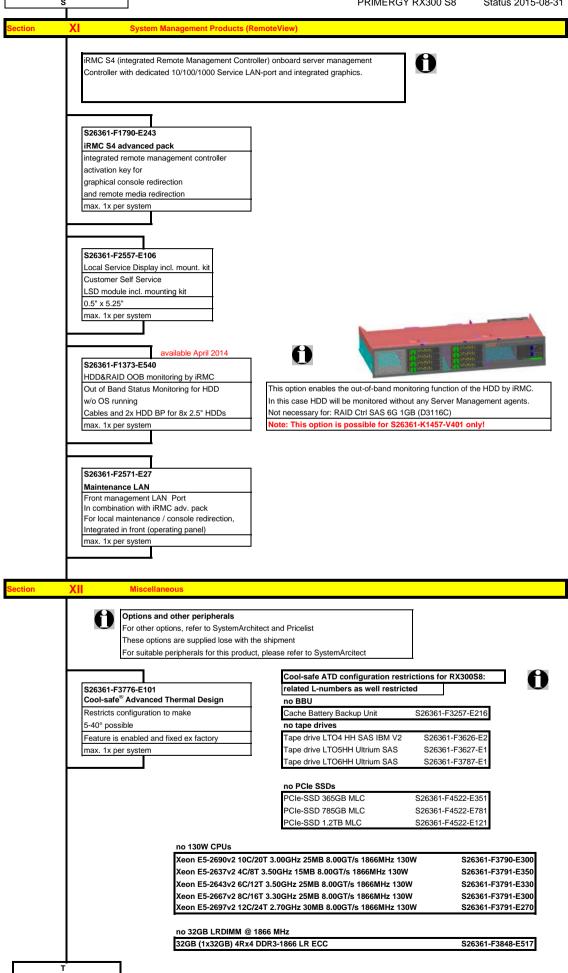
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т		System configurator and order-information guid PRIMERGY RX300 S8 Status 2015-08-3
ction XIII	Country specific power cord	
S26361-F1452-E100 REGION KIT APAC/E	S26361-F1452-E110 MEA/India REGION KIT JP	S26361-F1452-E130 REGION KIT America
For Shipments to Asia EMEA or India regions	pacific, For Shipments to Japan regions	
1x per system	1x per system	1x per system
Hint: N	· · · · · ·	urable with Certification for India and China (CCC)
T26139-Y1968-E100	Powercord for rack, 4m, grey,	
	IEC 320 C14 connector	
T26139-Y1742-E10	IEC 320 C14 connector USA, Canada, 1.8m, grey	
T26139-Y1742-E10 T26139-Y4024-E10		

	PRIMERGY RX300 S8 Status 20
XVI CCC exclusions	
S26361-F3301-E120	
CCC Certification for China	
Limits configuration in accordance	
with CCC exclusions	
max. 1x per system	
The following order components out of the excelling	
The following order components out of the specific are NOT allowed together with CCC Certification for	
Front-VGA Interface	S26361-F2571-E26
Tione VOA Intenace	320301-1 2371-L20
PCIe-SSD 365GB MLC	S26361-F4522-E351
PCIe-SSD 785GB MLC	S26361-F4522-E781
PCIe-SSD 1.2TB MLC	S26361-F4522-E121
PACC EP P3700 AIC 800GB	S26361-F5318-E800
PACC EP P3700 AIC 1.6TB	S26361-F5318-E161
PACC EP P3700 AIC 2TB	S26361-F5318-E201
SAS Ctrl 6G 8ext PCIe lp	S26361-F3628-E201
Shared 10Gb Management LAN Kit	S26361-F3629-E750
Modulare SV 800W titanium hp	S26113-F615-E10
Modulare SV DC -48V 800W gold hp	S26113-F609-E10
Cable powercord rack, 4m, grey	T26139-Y1968-E100
Ltg Netzanschluss -48V DC, 4m, schwarz	T26139-Y4024-E10
Leitung Netzanschluss (USA), 1,8m, grau	T26139-Y1742-E10
TPM Modul	S26361-F3552-E1

End PRIMERGY RX300 S8

Change Report

Date	Order number	Changes
2015-07-22		RAID controller updated
2015-07-21	S26361-F5520-E*	Added 2.5" SAS 12G 10K 512n HDDs
2015-02-27	S26361-F5520-E*	Added 2.5" SAS 6G 15K HDD up to 600GB within 3.5" Carrier
2014-11-28		2.5" & 3.5" Read-Intensive SATA SSDs added
2014-10-20	S26361-F5536-E2	added Emulex OCe14012 dual channel 10Gb NIC
2014-08-04	S26361-F5313-xxx	16Gb Qlogic added
2014-07-03	S26361-F5315-E*	Added 3.5" SAS 12G SSDs
2014-07-02	S26361-F3848-E517	No ATD functionality with 32GB LRDIMM @ 1866 MHz
2014-06-30	S26361-F3301-E123	Added certification for India
2014-06-16	S26361-F3740-xxx	EOL
2014-06-16	S26361-F3739-xxx	EOL
2014-06-16	S26361-F3242-E201 / -L201	EOL
2014-06-10	S26361-F5319-E*	Added 3.5" SATA 6G SSDs
2014-05-19	S26361-F3848-E517	Added 32 GB LRDIMM 1866 MHz
2014-05-06	S26361-F53250	new CNA OCe14102 added
2014-05-02		PCIe SSD SFF options removed
2014-04-03	S26361-F3776-E101	Cool-safe ATD restriction changed - 32GB and 64GB LRDIMM no more restricted
2014-03-18		SAS3.0 RAID Ctrl updated
2014-03-17	S26361-F3739-E201	phase out
2014-03-17	S26361-F3740-E201	phase out
2014-03-17	S26361-F3610-E202	EOL
2014-03-05	S26361-F1373-E540	HDD&RAID OOB monitoring by iRMC added
2014-01-30	S26361-F5303-*	New SATA SSDs added.
2014-01-30	S26361-F5297-*	New SAS 12G SSDs added.
2013-12-12	S26361-F3554-E8	restricted for ATD
2013-11-29	S26361-F3837-L64	SATA DOM (Disk on module) added
2013-11-27	S26361-F3301-E120	Restrictions CCC Certification for China updated
2013-10-28		SSD support with On-Board controller.
2013-10-28		restriction for 2.5" BC-SAS HDD with "*F3554-E8" removed.
2013-10-18	optional USB Comps	no longer available
2013-10-16	S26361-F4610-E202 / -E204	added new 1Gb NICs from Intel
2013-10-09	S26113-F615-E10	add comment "110V range not supported"
2013-10-08		restrictions for Cool-safe ATD added
2013-09-19		Memory hint on CPU page extended
2013-09-13	S26361-F5247-E112	HDD 1.2TB SAS 10K added.
2013-09-03	RMK	CMA not longer a must component
2013-09-01		First Release
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